



Material Content Data Sheet



Sales Product Name		TLE6251D		Issued		9. January 2019		
MA#		MA004419028						
Package		PG-DSO-8-16		Weight*		83.37 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.799	3.36	3.36	33576	33576
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8602	
wire	non noble metal	copper	7440-50-8	29.121	34.93	35.84	349295	358435
	noble metal	gold	7440-57-5	0.133	0.16	0.16	1595	1595
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1144
encapsulation	plastics	epoxy resin	-	4.389	5.26		52645	
	inorganic material	silicondioxide	60676-86-0	43.223	51.85	57.22	518443	572232
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9762	9762
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7799	7799
glue	plastics	acrylic resin	-	0.305	0.37		3652	
	noble metal	silver	7440-22-4	1.080	1.29	1.66	12949	16601
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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